



TCA9517A 电平转换 I²C 总线中继器

1 特性

- 双通道双向缓冲器
- 与 I²C 总线和系统管理总线 (SMBus) 兼容
- 在 A 侧上, 运行电源电压范围为 0.9V 至 5.5V
- 在 B 侧上, 运行电源电压范围为 2.7V 至 5.5V
- 从 0.9V-5.5V 到 2.7V-5.5V 的电压电平转换
- 针对 PCA9515B 的封装和功能替代产品
- 高电平有效中继器启用输入
- 漏极开路 I²C I/O
- 5.5V 耐压 I²C 和使能输入支持混合模式信号操作
- 适用于标准模式和快速模式 I²C 器件和多重主器件
- 器件断电时 I²C 引脚呈高阻态
- 锁断性能超过 100mA, 符合 JESD 78 II 类规范的要求
- 静电放电 (ESD) 保护性能超过 JESD 22 规范的要求
 - 5500V 人体放电模式 (A114-A)
 - 200V 机器放电模式 (A115-A)
 - 1000V 组件充电模式 (C101)

2 应用范围

- 服务器
- 路由器 (电信交换设备)
- 工业设备
- 具有多个 I²C 从器件和/或印刷电路板 (PCB) 走线较长的产品

3 说明

TCA9517A 是一款具有电平转换功能的双向缓冲器, 适用于 I²C 和 SMBus 系统。它能够在混合模式应用中实现低压 (低至 0.9V) 和高压 (2.7V 至 5.5V) 之间的双向电压电平转换 (升压转换/降压转换)。该器件能够扩展 I²C 和 SMBus 系统, 甚至在电平转换期间也不会影响系统性能。

TCA9517A 可缓冲 I²C 总线上的串行数据 (SDA) 和串行时钟 (SCL) 信号, 因此允许 I²C 应用中的两条总线连接高达 400pF 的总线电容。

TCA9517A 具有两类驱动器: A 侧驱动器和 B 侧驱动器。所有输入和 I/O 均可耐受 5.5V 过压, 甚至在器件断电时 (V_{CCB} 和/或 $V_{CCA} = 0V$) 也如此。

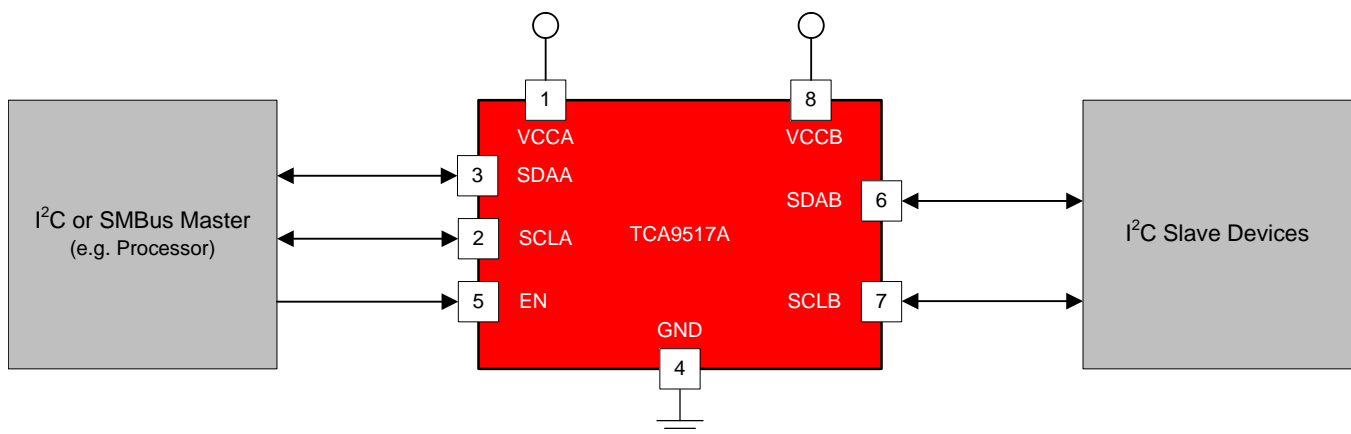
TCA9517A 的竞争电平阈值 (V_{ILC}) 高于 TCA9517, 允许连接下拉能力较弱的从器件。

器件信息⁽¹⁾

器件型号	封装	封装尺寸 (标称值)
TCA9517A	VSSOP (8)	3.00mm × 3.00mm

(1) 要了解所有可用封装, 请见数据表末尾的可订购产品附录。

简化电路原理图



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4 修订历史记录

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision A (April 2013) to Revision B	Page
• 已添加 引脚配置和功能部分, ESD 额定值表, 特性描述部分, 器件功能模式, 应用和实施部分, 电源相关建议部分, 布局部分, 器件和文档支持部分以及机械、封装和可订购信息部分	1
• 已删除订购信息表。	3

Changes from Original (December 2012) to Revision A	Page
• 更新了订购信息表的顶部标记列。	3

5 说明（续）

B 侧上的缓冲器设计类型会阻止其与具有静态电压偏移的器件搭配使用。这是因为这类器件并不将经缓冲的低电平信号识别为有效低电平，并且不再将其作为经缓冲的低电平进行传送。

B 侧驱动器运行电压介于 **2.7V** 至 **5.5V** 之间。针对这个内部缓冲器的输出低电平大约为 **0.5V**，但是当输出在内部被驱动为低电平时，输入电压必须比输出低电平低 **70mV** 或者更多。更高的电压低信号被称为经缓冲的低电平。当 **B** 侧 I/O 被内部驱动为低电平时，输入并不将此低电平识别为低电平。当输入低电平状态被释放时，这一特性防止了锁定情况的发生。

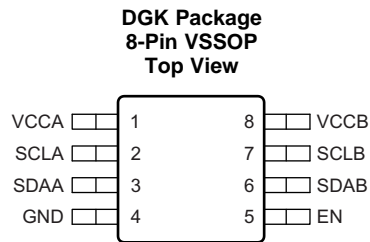
A 侧驱动器运行电压介于 **0.9V** 至 **5.5V** 之间并且能够驱动更大电流。它们不需要经缓冲的低电平特性（或者静态偏移电压）。这意味着，**B** 侧上的低电平信号将转换为 **A** 侧上接近 **0V** 的低电平，以适应低压逻辑的较小电压摆幅。**A** 侧上的输出下拉电阻会驱动一个“硬”低电平，输入电平会设置在 $0.3 \times V_{CCA}$ 以满足低压侧电源电压低至 **0.9V** 的系统对于较低低电平的需求。

可以将两个及以上 **TCA9517A** 的 **A** 侧连接在一起，从而构成多种拓扑结构（请参见 [Figure 8](#) 和 [Figure 9](#)），其中 **A** 侧作为公共总线。此外，还可以将 **A** 侧直接连接至任意具有静态或动态偏移电压的其他缓冲器。可以将多个 **TCA9517A** 串联在一起（相邻器件间通过 **A** 侧和 **B** 侧相连），偏移电压不会增大，只是需要考虑飞行时间延迟。由于 **B** 侧缓冲低电压的原因，**TCA9517A** 不能通过 **B** 侧相连。**B** 侧不能连接配有上升时间加速器的器件。

VCCA 只能用于为 **A** 侧输入比较器提供 $0.3 \times V_{CCA}$ 参考电压，或者用于电源正常状态检测电路。**TCA9517A** 逻辑和所有 I/O 均由 **VCCB** 引脚供电。

当与标准 **I²C** 系统一同工作时，需要用上拉电阻在经缓冲的总线上提供逻辑高电平。**TCA9517A** 具有 **I²C** 总线的标准漏极开路配置。这些上拉电阻器的尺寸由系统决定，然而，中继器的每一侧都必须有一个上拉电阻器。此器件专为与标准模式及快速模式 **I²C** 器件（而不单是 **SMBus** 器件）一起工作而设计。在可以接受标准模式器件和多个主控器的通用型 **IC** 系统中，标准模式 **I²C** 器件的额定值只为 **3mA**。在特定条件下，可以采用更高的终止电流。

6 Pin Configuration and Functions



Pin Functions

PIN		TYPE	DESCRIPTION
NO.	NAME		
1	VCCA	Supply	A-side supply voltage (0.9 V to 5.5 V)
2	SCLA	Input/Output	Serial clock bus, A-side. Connect to V_{CCA} through a pull-up resistor. If unused, connect directly to ground.
3	SDAA	Input/Output	Serial data bus, A-side. Connect to V_{CCA} through a pull-up resistor. If unused, connect directly to ground.
4	GND	Ground	Ground
5	EN	Input	Active-high repeater enable input
6	SDAB	Input/Output	Serial data bus, B-side. Connect to V_{CCB} through a pull-up resistor. If unused, connect directly to ground.
7	SCLB	Input/Output	Serial clock bus, B-side. Connect to V_{CCB} through a pull-up resistor. If unused, connect directly to ground.
8	VCCB	Supply	B-side and device supply voltage (2.7 V to 5.5 V)

7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

			MIN	MAX	UNIT
V_{CCB}	Supply voltage range		–0.5	7	V
V_{CCA}	Supply voltage range		–0.5	7	V
V_I	Enable input voltage range ⁽²⁾		–0.5	7	V
$V_{I/O}$	I ² C bus voltage range ⁽²⁾		–0.5	7	V
I_{IK}	Input clamp current	$V_I < 0$		–50	mA
I_{OK}	Output clamp current	$V_O < 0$		–50	
I_O	Continuous output current			±50	mA
	Continuous current through V_{CC} or GND			±100	mA
T_{stg}	Storage temperature range		–65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

7.2 ESD Ratings

		VALUE	UNIT
V _(ESD) Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±5500	V
	Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±1000	
	Machine model (A115-A)	±200	

(1) JEDEC document JEP155 states that 500 V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250 V CDM allows safe manufacturing with a standard ESD control process.

7.3 Recommended Operating Conditions

		MIN	MAX	UNIT
V _{CCA}	Supply voltage, A-side bus	0.9 ⁽¹⁾	5.5	V
V _{CCB}	Supply voltage, B-side bus	2.7	5.5	V
V _{IH}	High-level input voltage	SDAA, SCLA	0.7 × V _{CCA}	V
		SDAB, SCLB	0.7 × V _{CCB}	
		EN	0.7 × V _{CCB}	
V _{IL}	Low-level input voltage	SDAA, SCLA	0.3 × V _{CCA}	V
		SDAB, SCLB ⁽²⁾	0.3 × V _{CCB}	
		EN	0.3 × V _{CCB}	
I _{OL}	Low-level output current		6	mA
T _A	Operating free-air temperature	–40	85	°C

(1) Low-level supply voltage

(2) V_{IL} specification is for the first low level seen by the SDAB and SCLB lines. V_{ILC} is for the second and subsequent low levels seen by the SDAB and SCLB lines. See [V_{ILC} and Pullup Resistor Sizing](#) for V_{ILC} application information

7.4 Thermal Information

THERMAL METRIC ⁽¹⁾		TCA9517A	UNIT
		DGK (VSSOP)	
		8 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	187.6	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	59.3	°C/W
R _{θJB}	Junction-to-board thermal resistance	108.6	°C/W
ψ _{JT}	Junction-to-top characterization parameter	3.4	°C/W
ψ _{JB}	Junction-to-board characterization parameter	106.9	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

7.5 Electrical Characteristics

 $V_{CCB} = 2.7\text{ V to }5.5\text{ V}$, $GND = 0\text{ V}$, $T_A = -40^\circ\text{C to }85^\circ\text{C}$ (unless otherwise noted)

PARAMETER			TEST CONDITIONS	V _{CCB}	MIN	TYP	MAX	UNIT
V _{IK}	Input clamp voltage		I _I = −18 mA	2.7 V to 5.5 V			−1.2	V
V _{OL}	Low-level output voltage	SDAB, SCLB	I _{OL} = 100 μA or 6 mA, V _{ILA} = V _{ILB} = 0 V	2.7 V to 5.5 V	0.45	0.52	0.6	V
		SDAA, SCLA	I _{OL} = 6 mA				0.1	
V _{OL} − V _{ILC}	Low-level input voltage below low-level output voltage	SDAB, SCLB	ensured by design	2.7 V to 5.5 V		70		mV
V _{ILC}	SDA and SCL low-level input voltage contention	SDAB, SCLB		2.7 V to 5.5 V		0.45		V
I _{CC}	Quiescent supply current for V _{CCA}		Both channels low, SDAA = SCLA = GND and SDAB = SCLB = open, or SDAA = SCLA = open and SDAB = SCLB = GND				1	mA
I _{CC}	Quiescent supply current		Both channels high, SDAA = SCLA = V _{CCA} and SDAB = SCLB = V _{CCB} and EN = V _{CCB}	5.5 V		1.5	5	mA
			Both channels low, SDAA = SCLA = GND and SDAB = SCLB = open			1.5	5	
			In contention, SDAA = SCLA = GND and SDAB = SCLB = GND			3	5	
I _I	Input leakage current	SDAB, SCLB	V _I = V _{CCB}	2.7 V to 5.5 V			±1	μA
			V _I = 0.2 V				10	
		SDAA, SCLA	V _I = V _{CCB}				±1	
			V _I = 0.2 V				10	
		EN	V _I = V _{CCB}				±1	
			V _I = 0.2 V			−10	−30	
I _{OH}	High-level output leakage current	SDAB, SCLB	V _O = 3.6 V	2.7 V to 5.5 V			10	μA
		SDAA, SCLA					10	
C _I	Input capacitance	EN	V _I = 3 V or 0 V	3.3 V		6	10	pF
		SCLA, SCLB	V _I = 3 V or 0 V	3.3 V		8	13	
				0 V		7	11	
C _{IO}	Input/output capacitance	SDAA, SDAB	V _I = 3 V or 0 V	3.3 V		8	13	pF
				0 V		7	11	

7.6 Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted)

	MIN	MAX	UNIT
t_{su} Setup time, EN high before Start condition ⁽¹⁾	100		ns
t_h Hold time, EN high after Stop condition ⁽¹⁾	100		ns

(1) EN should change state only when the global bus and the repeater port are in an idle state.

7.7 I²C Interface Switching Characteristics

 $V_{CCB} = 2.7\text{ V to }5.5\text{ V}$, $GND = 0\text{ V}$, $T_A = -40^\circ\text{C to }85^\circ\text{C}$ (unless otherwise noted)^{(1) (2)}

PARAMETER		FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP ⁽³⁾	MAX	UNIT
t_{PLZ}	Propagation delay	SDAB, SCLB ⁽⁴⁾ (see Figure 6)	SDAA, SCLA ⁽⁴⁾ (see Figure 6)		80	141	350	ns
		SDAA, SCLA ⁽⁵⁾ (see Figure 5)	SDAB, SCLB ⁽⁵⁾ (see Figure 5)		25	74	110	
t_{PZL}	Propagation delay	SDAB, SCLB	SDAA, SCLA	$V_{CCA} \leq 2.7\text{ V}$ (see Figure 4)	30	76 ⁽⁶⁾	110	ns
				$V_{CCA} \geq 3\text{ V}$ (see Figure 4)	10	86	230	
		SDAA, SCLA ⁽⁵⁾ (see Figure 5)	SDAB, SCLB ⁽⁵⁾ (see Figure 5)		60	107	230	
t_{TLH}	Transition time	80%	20%	$V_{CCA} \leq 2.7\text{ V}$ (see Figure 5)	10	12	15	ns
				$V_{CCA} \geq 3\text{ V}$ (see Figure 5)	40	42	45	
					110	125	140	
t_{THL}	Transition time	80%	20%	$V_{CCA} \leq 2.7\text{ V}$ (see Figure 5)	1	52 ⁽⁶⁾	105	ns
				$V_{CCA} \geq 3\text{ V}$ (see Figure 5)	20	67	175	
					30	48	90	

- (1) Times are specified with loads of 1.35-k Ω pull-up resistance and 50-pF load capacitance on the B-side and 167- Ω pull-up and 57-pF load capacitance on the A side. Different load resistance and capacitance alter the RC time constant, thereby changing the propagation delay and transition times.
- (2) pull-up voltages are V_{CCA} on the A side and V_{CCB} on the B-side.
- (3) Typical values were measured with $V_{CCA} = V_{CCB} = 3.3\text{ V}$ at $T_A = 25^\circ\text{C}$, unless otherwise noted.
- (4) The t_{PLH} delay data from B to A side is measured at 0.4 V on the B-side to 0.5 V_{CCA} on the A side when V_{CCA} is less than 2 V, and 1.5 V on the A side if V_{CCA} is greater than 2 V.
- (5) The proportional delay data from A to B-side is measured at 0.3 V_{CCA} on the A side to 1.5 V on the B-side.
- (6) Typical value measured with $V_{CCA} = 2.7\text{ V}$ at $T_A = 25^\circ\text{C}$

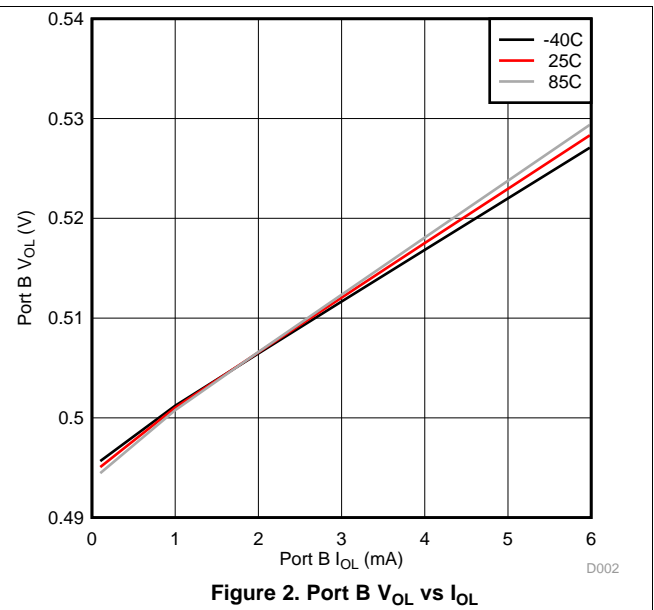
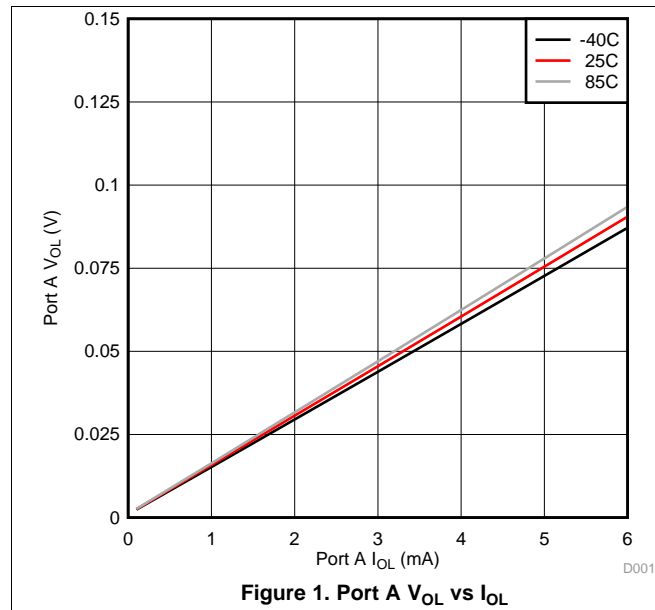
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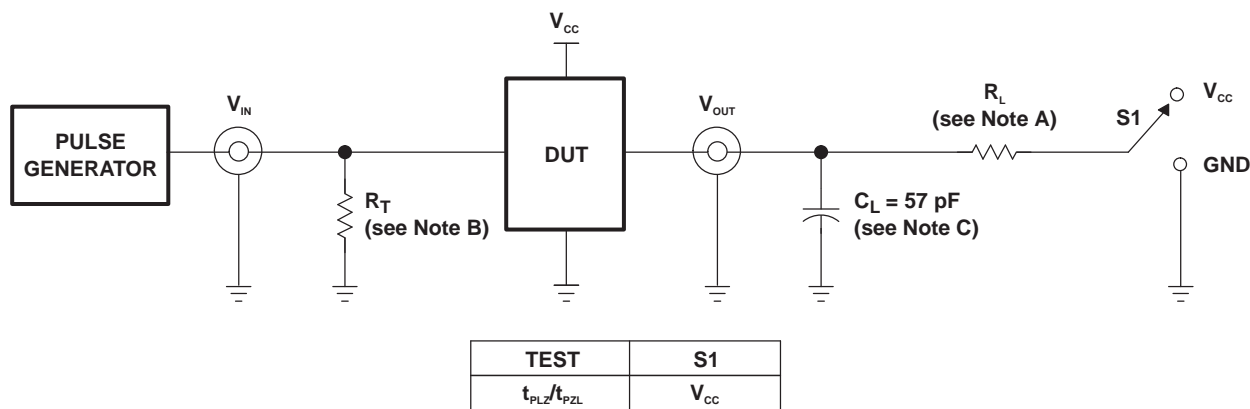
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7.8 Typical Characteristics

$V_{CCA} = 0.9\text{ V}$, $V_{CCB} = 2.7\text{ V}$



8 Parameter Measurement Information



TEST CIRCUIT FOR OPEN-DRAIN OUTPUT

- A. $R_L = 167 \Omega$ (0.9 V to 2.7 V) and $R_L = 450 \Omega$ (3.0 V to 5.5 V) on the A side and 1.35 k Ω on the B-side
- B. R_T termination resistance should be equal to Z_{OUT} of pulse generators.
- C. C_L includes probe and jig capacitance.
- D. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, $Z_O = 50 \Omega$, slew rate ≥ 1 V/ns.
- E. The outputs are measured one at a time, with one transition per measurement.
- F. t_{PLH} and t_{PHL} are the same as t_{pd} .
- G. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- H. t_{PZL} and t_{PZH} are the same as t_{en} .

Figure 3. Test Circuit

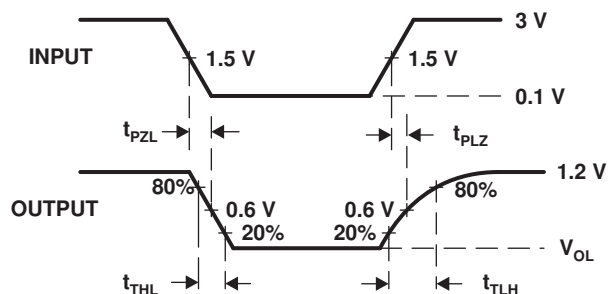


Figure 4. Waveform 1 – Propagation Delay and Transition Times for B-side to A-side

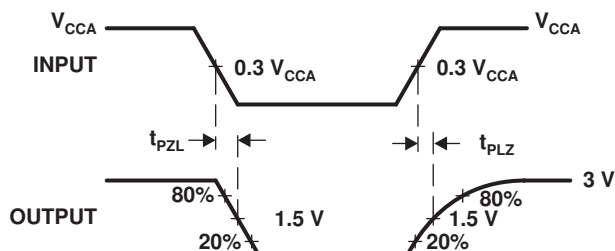


Figure 5. Waveform 2 – Propagation Delay and Transition Times for A-side to B-side

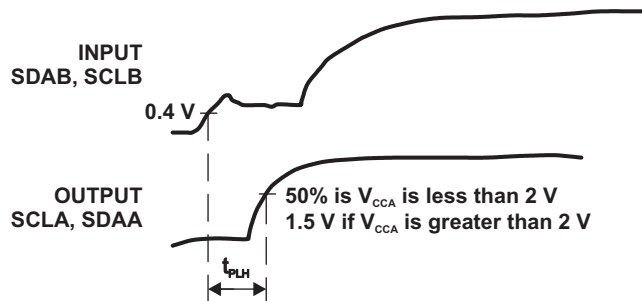


Figure 6. Waveform 3 – Propagation Delay for B-side to A-side

9 Detailed Description

9.1 Overview

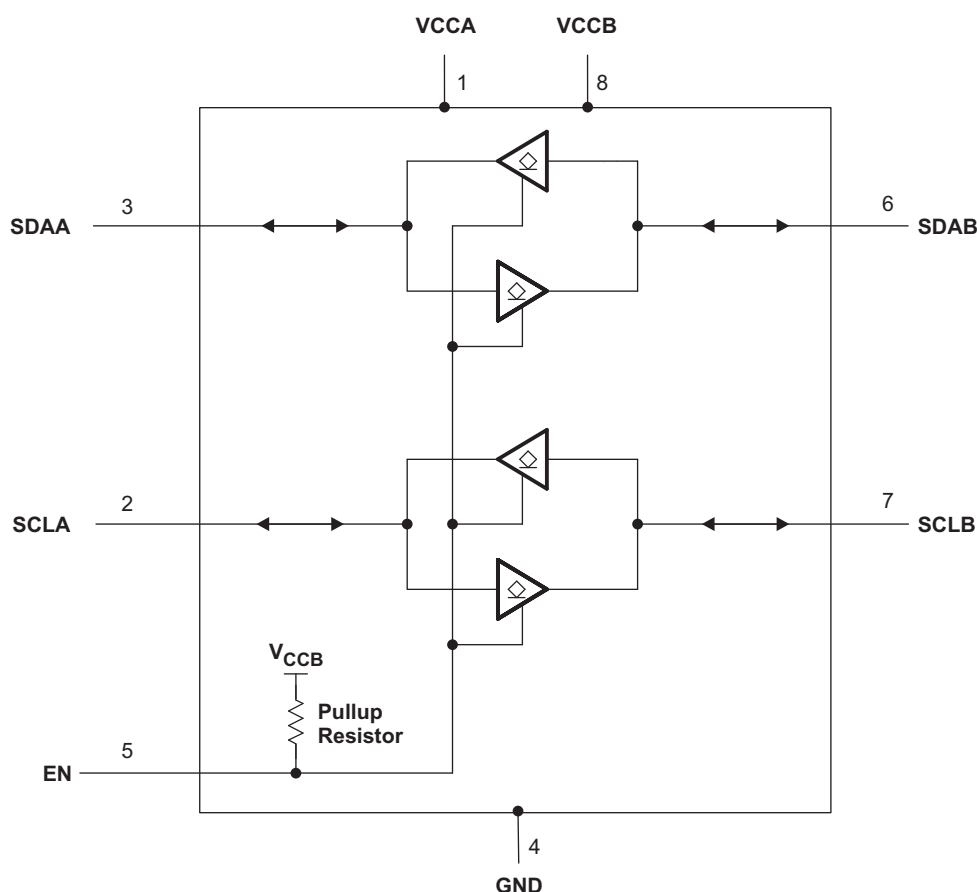
The TCA9517A is a bidirectional buffer with level shifting capabilities for I²C and SMBus systems. It provides bidirectional voltage-level translation (up-translation/down-translation) between low voltages (down to 0.9 V) and higher voltages (2.7 V to 5.5 V) in mixed-mode applications. This device enables I²C and SMBus systems to be extended without degradation of performance, even during level shifting.

The TCA9517A buffers both the serial data (SDA) and the serial clock (SCL) signals on the I²C bus, thus allowing two buses of up to 400-pF bus capacitance to be connected in an I²C application.

The TCA9517A has two types of drivers: A-side drivers and B-side drivers. All inputs and I/Os are over-voltage tolerant to 5.5 V, even when the device is unpowered (V_{CCB} and/or $V_{CCA} = 0$ V).

The TCA9517A offers a higher contention level threshold, V_{ILC} , than the TCA9517, which allows connections to slaves which have weaker pull-down ability.

9.2 Functional Block Diagram



9.3 Feature Description

9.3.1 Two-Channel Bidirectional Buffer

The TCA9517A is a two-channel bidirectional buffer with level-shifting capabilities

9.3.2 Active-High Repeater-Enable Input

The TCA9517A has an active-high enable (EN) input with an internal pull-up to V_{CCB} , which allows the user to select when the repeater is active. This can be used to isolate a badly behaved slave on power-up reset. The EN input should change state only when the global bus and repeater port are in an idle state, to prevent system failures.

9.3.3 V_{OL} B-Side Offset Voltage

The B-side drivers operate from 2.7 V to 5.5 V. The output low level for this internal buffer is approximately 0.5 V, but the input voltage must be 70 mV or more below the output low level when the output internally is driven low. The higher-voltage low signal is called a buffered low. When the B-side I/O is driven low internally, the low is not recognized as a low by the input. This feature prevents a lockup condition from occurring when the input low condition is released. This type of design prevents 2 B-side ports from being connected to each other.

9.3.4 Standard Mode and Fast Mode Support

The TCA9517A supports standard mode as well as fast mode I^2C . The maximum system operating frequency will depend on system design and the delays added by the repeater.

9.3.5 Clock Stretching Support

The TCA9517A can support clock stretching, but care needs to be taken to minimize the overshoot voltage presented during the hand-off between the slave and master. This is best done by increasing the pull-up resistor value.

9.4 Device Functional Modes

Table 1. Function Table

INPUT EN	FUNCTION
L	Outputs disabled
H	SDAA = SDAB SCLA = SCLB

10 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

10.1 Application Information

A typical application is shown in Figure 7. In this example, the system master is running on a 3.3 V I²C bus, and the slave is connected to a 1.2 V I²C bus. Both buses run at 400 kHz. Master devices can be placed on either bus.

The TCA9517A is 5-V tolerant, so it does not require any additional circuitry to translate between 0.9 V to 5.5 V bus voltages and 2.7 V to 5.5 V bus voltages.

When the A side of the TCA9517A is pulled low by a driver on the I²C bus, a comparator detects the falling edge when it goes below $0.3 \times V_{CCA}$ and causes the internal driver on the B-side to turn on, causing the B-side to pull down to about 0.5 V. When the B-side of the TCA9517A falls, first a CMOS hysteresis-type input detects the falling edge and causes the internal driver on the A side to turn on and pull the A-side pin down to ground. In order to illustrate what would be seen in a typical application, refer to Figure 9 and Figure 10. If the bus master in Figure 7 were to write to the slave through the TCA9517A, waveforms shown in Figure 9 would be observed on the A bus. This looks like a normal I²C transmission, except that the high level may be as low as 0.9 V, and the turn on and turn off of the acknowledge signals are slightly delayed.

On the B-side bus of the TCA9517A, the clock and data lines would have a positive offset from ground equal to the V_{OL} of the TCA9517A. After the eighth clock pulse, the data line is pulled to the V_{OL} of the slave device, which is very close to ground in this example. At the end of the acknowledge, the level rises only to the low level set by the driver in the TCA9517A for a short delay, while the A-bus side rises above $0.3 \times V_{CCA}$ and then continues high.

10.2 Typical Application

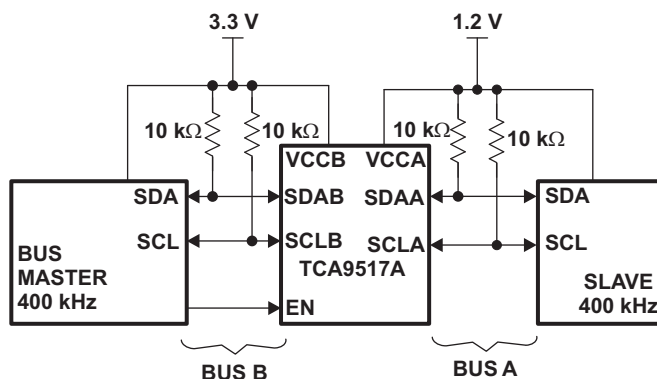


Figure 7. Typical Application Schematic

10.2.1 Design Requirements

For the level translating application, the following should be true:

- $V_{CCA} = 0.9 \text{ V to } 5.5 \text{ V}$
- $V_{CCB} = 2.7 \text{ to } 5.5 \text{ V}$
- $V_{CCA} < V_{CCB}$
- B-side ports must not be connected together

Typical Application (continued)

10.2.2 Detailed Design Procedure

10.2.2.1 Clock Stretching Support

The TCA9517A can support clock stretching, but care needs to be taken to minimize the overshoot voltage presented during the hand-off between the slave and master. This is best done by increasing the pull-up resistor value.

10.2.2.2 V_{ILC} and Pullup Resistor Sizing

For the TCA9517A to function correctly, all devices on the B-side must be able to pull the B-side below the voltage input low contention level (V_{ILC}). This means that the V_{OL} of any device on the B-side must be below 0.45 V.

V_{OL} of a device can be adjusted by changing the I_{OL} through the device which is set by the pull-up resistance value. The pull-up resistance on the B-side must be carefully selected to ensure that logic levels will be transferred correctly to the A-side.

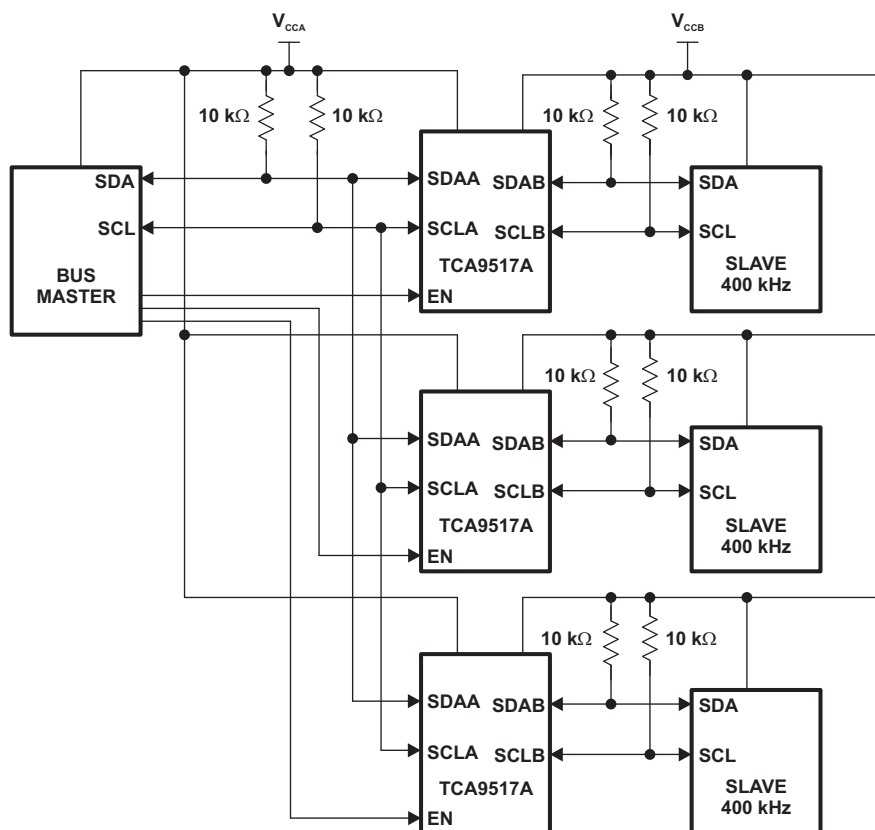


Figure 8. Typical Star Application

Multiple A sides of TCA9517As can be connected in a star configuration, allowing all nodes to communicate with each other.

Typical Application (continued)

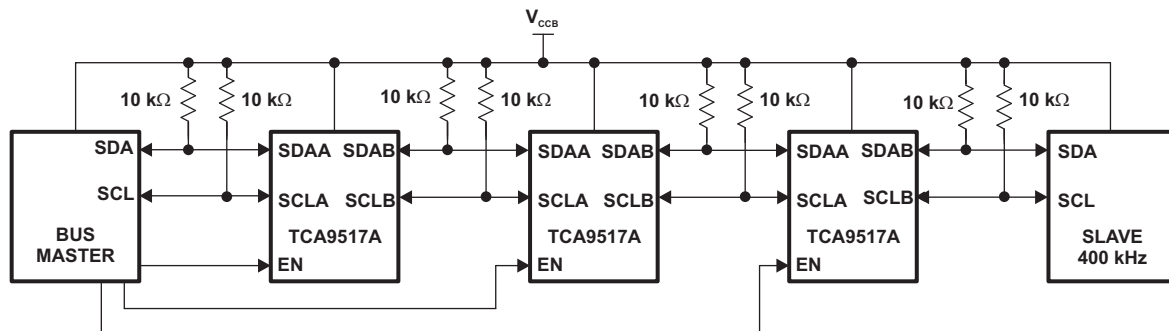


Figure 9. Typical Series Application

To further extend the I²C bus for long traces/cables, multiple TCA9517As can be connected in series as long as the A-side is connected to the B-side. I²C bus slave devices can be connected to any of the bus segments. The number of devices that can be connected in series is limited by repeater delay/time-of-flight considerations on the maximum bus speed requirements.

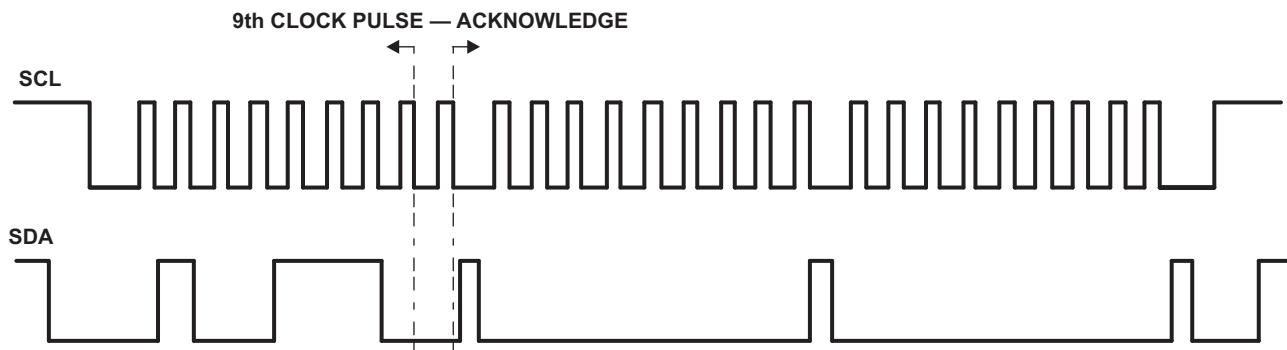


Figure 10. Bus A (0.9 V to 5.5 V Bus) Waveform

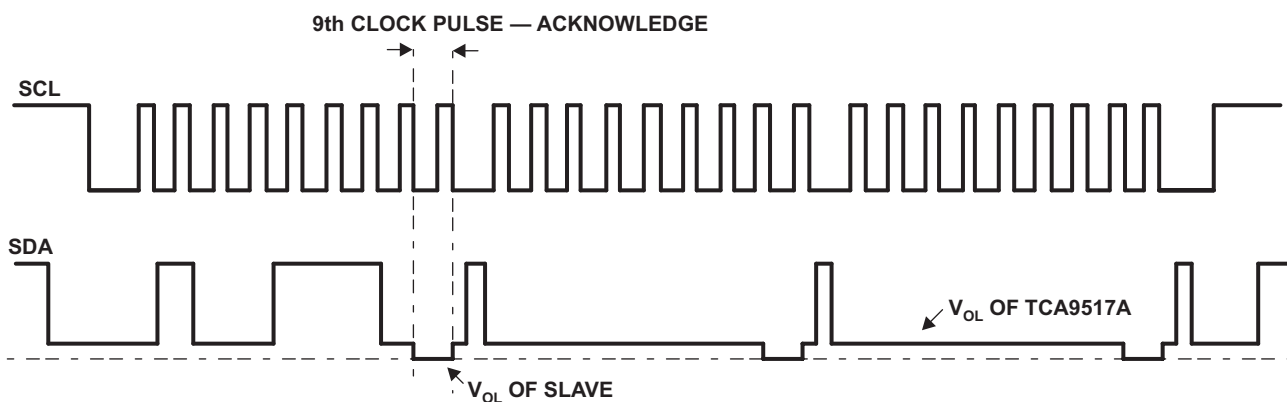
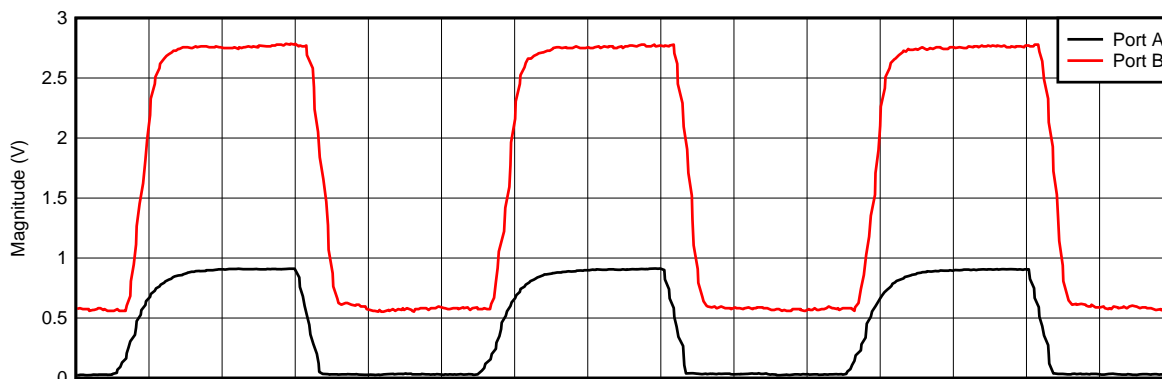


Figure 11. Bus B (2.7 V to 5.5 V Bus) Waveform

Typical Application (continued)

10.2.3 Application Curve



D003

Figure 12. Voltage Translation at 400 kHz, $V_{CCA} = 0.9\text{ V}$, $V_{CCB} = 2.7\text{ V}$

11 Power Supply Recommendations

V_{CCB} and V_{CCA} can be applied in any sequence at power up. The TCA9517A includes a power-up circuit that keeps the output drivers turned off until V_{CCB} is above 2.5 V and the V_{CCA} is above 0.8 V. After power up and with the EN high, a low level on the A-side (below $0.3 \times V_{CCA}$) turns the corresponding B-side driver (either SDA or SCL) on and drives the B-side down to approximately 0.5 V. When the A-side rises above $0.3 \times V_{CCA}$, the B-side pull-down driver is turned off and the external pull-up resistor pulls the pin high. When the B-side falls first and goes below $0.3 \times V_{CCB}$, the A-side driver is turned on and the A-side pulls down to 0 V. The B-side pull-down is not enabled unless the B-side voltage goes below 0.4 V. If the B-side low voltage does not go below 0.5 V, the A-side driver turns off when the B-side voltage is above $0.7 \times V_{CCB}$. If the B-side low voltage goes below 0.4 V, the B-side pull-down driver is enabled, and the B-side is able to rise to only 0.5 V until the A-side rises above $0.3 \times V_{CCA}$.

TI recommends using a decoupling capacitor and placing it close to the V_{CCA} and V_{CCB} pins of a value of about 100 nF.

12 Layout

12.1 Layout Guidelines

There are no special layout procedures required for the TCA9517A.

It is recommended that the decoupling capacitors be placed as close to the VCC pins as possible.

12.2 Layout Example

Figure 13 shows an example layout of the DGK package.

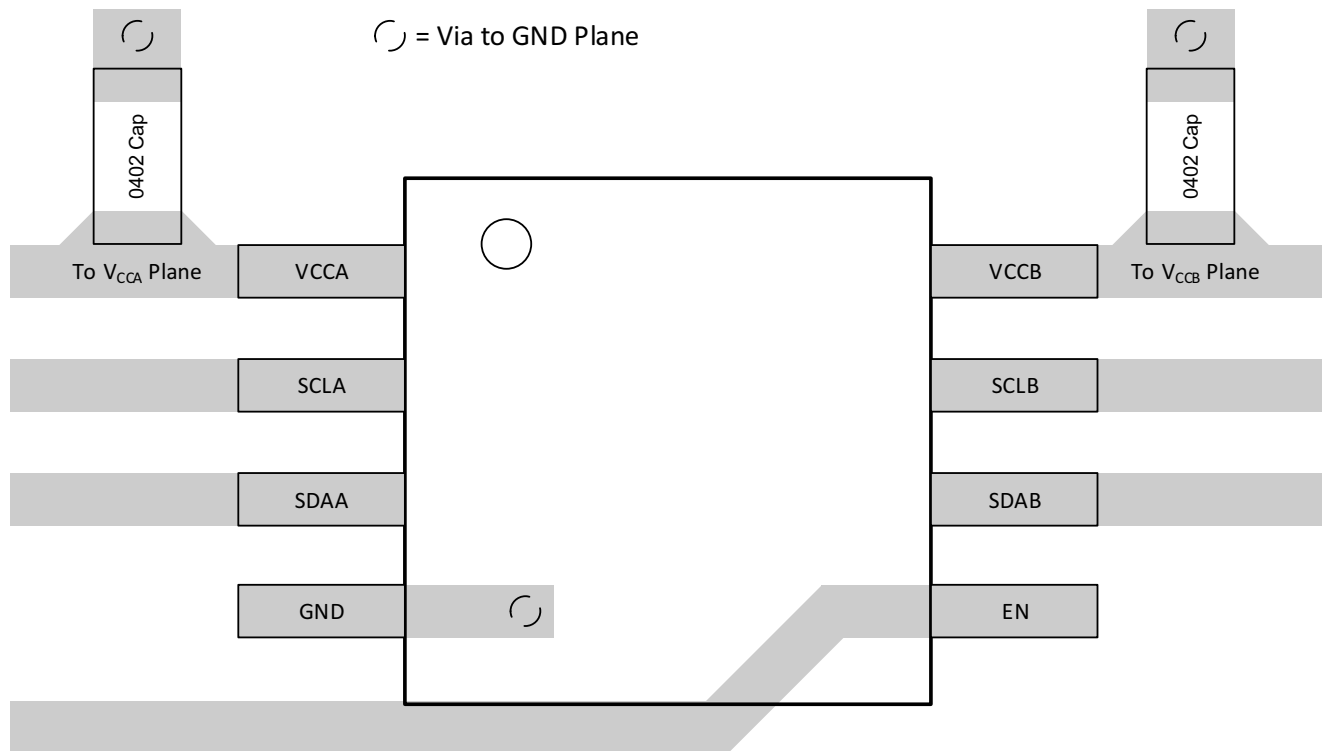


Figure 13. TCA9517A Layout Example

13 器件和文档支持

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13.4 术语表

SLYZ022 — *TI* 术语表。

这份术语表列出并解释术语、首字母缩略词和定义。

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TCA9517ADGKR	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	BSK	Samples

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TCA9517ADGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



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DGK (S-PDSO-G8)

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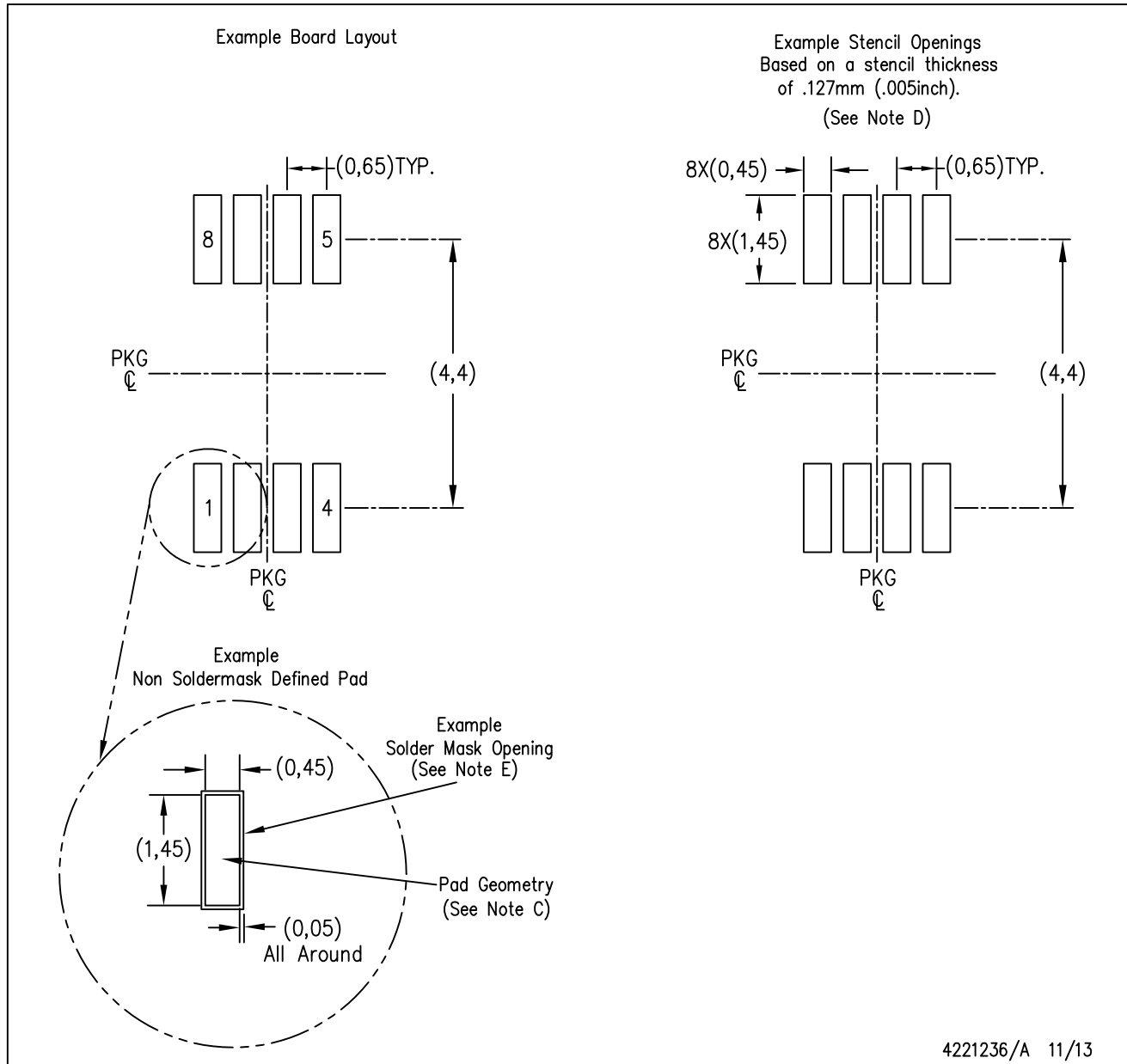


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